**Material Set Change:**

|  |  |  |  |
| --- | --- | --- | --- |
| Package Material Set | | Carsem | ASE Chungli |
| SOIC\_N  SOIC\_W  SOIC\_IC | Die Attach | Ablestik 84-1LMISR4 | Hitachi EN4900GC |
| Mold Compound | Sumitomo 6600H or G600C | Sumitomo G700LY |
| Wire | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire |

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| Package Material Set | | Carsem | ASE Chungli |
| SOIC\_N  SOIC\_W  SOIC\_IC | Die Attach | Ablestik 84-3J | Ablestik 2025D |
| Mold Compound | Sumitomo 6600H or G600C | Sumitomo G700LY |
| Wire | 1.0mil and 1.3 mil Gold Wire | 1.0mil and 1.3mil Gold Wire |